

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 247830US20CONT		SERIAL NO. 10/762,318	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Qin-Yi TONG			
				FILING DATE January 23, 2004		GROUP 2823	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
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	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES      NO		
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)</b>							
JH	AU	Andreas Plossl et al., "THE INTERFACE OF SILICON SAMPLES JOINED AT ROOM TEMPERATURE BY WAFER DIRECT BONDING IN ULTRAHIGH VACUUM", Preceedings of the Eighth International Symposium on Silicon Materials Science and Technology, Vol. 2, pp. 1361-1372, 1998.					
JH	AV	C. Gui et al, "PRESENT AND FUTURE ROLE OF CHEMICAL MECHANICAL POLISHING IN WAFER BONDING", Journal of the Electrochemical Society, Vol. 145, No. 6, pp. 2198-2204, June 1998.					
JH	AW	Hideki Takagi et al., "LOW-TEMPERATURE DIRECT BONDING OF SILICON AND SILICON DIOXIDE BY THE SURFACE ACTIVATION METHOD", Sensors and Actuators A, Vol. 70, No. 1-2, pp. 164-170, October 1, 1998.					
	AX						
	AY						<input type="checkbox"/> Additional References sheet(s) attached
Examiner <i>Barbara A. Garcia</i>					Date Considered <i>July 05, 2007</i>		
<small>*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							